

ABSTRACT OF THE DISCLOSURE

In a semiconductor device (1), semiconductor elements (2) and (3) are mounted on a lead frame (5) having leads (4). The semiconductor elements (2) and (3) are connected with the leads (4) by metallic wires (6) and (7). The semiconductor device (1) also has a heat sink (8). The members (2) to (8) are sealed with a plastic package (10). The leads (4) are exposed outward. Each of the end leads (4a) to (4d) has a wide first lead portion, a narrow second lead portion, a third lead portion to be inserted into an external substrate, and a protruding gap-controlling portion (9) for keeping the gap between the semiconductor device (1) and the external substrate constant. Because the heat resistance from the leads (4) to the plastic package (10) increases, the temperature-rise property of the lead is improved so that the solderability is improved.